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Part Number:

0737690200

Status:

Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 72 Circuits, Stack Height 6.05mm

Documents:

3D Model

Product Specification PS-73780-999-001 (PDF)

Drawing (PDF)

Packaging Specification PK-70873-0875-001 (PDF)

3D Model (PDF)

RoHS Certificate of Compliance (PDF)

General

Product Family

Backplane Connectors

Series

73769

Application

Backplane, Mezzanine

Component Type

PCB Header

Overview

HDM Backplane Connector System

Product Name

HDM

UPC

800754835503

Physical

Circuits (Loaded)

72

Circuits (maximum)

72

Color - Resin

Black

Durability (mating cycles max)

200

First Mate / Last Break

No

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin-Lead

Material - Resin

High Temperature Thermoplastic

Net Weight

6.634/g

Number of Columns

12

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length

3.50mm

PCB Locator

No

PCB Retention

None

PCB Thickness - Recommended

1.40mm

Packaging Type

Tube

Pitch - Mating Interface

2.00mm

Plating min - Mating

0.762µm

Plating min - Termination

0.381µm

Polarized to PCB

No

Stackable

Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55° to +105°C

Termination Interface: Style

Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact

1.0A

Data Rate

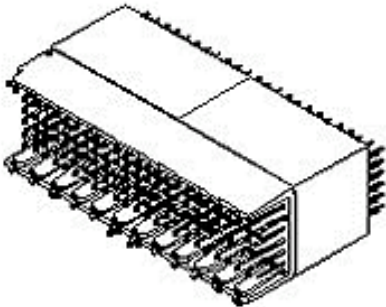
1.0 Gbps

Real Signals (per 25mm)

72

Voltage - Maximum

100V AC



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

China RoHS

Compliant

REACH SVHC

Not Contained Per - D(2020)9139-DC (19 Jan 2021)

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS

Green Image

ELV

Not Relevant

RoHS Phthalates

Not Contained

Search Parts in this Series

73769 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description

Product #

Backplane Signal Insertion Module Press-In Tool for 2.00mm Pitch HDM* Board-to-Board Backplane Header

622008502

Solder Process Data

Lead-free	Process Capability	N/A
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Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0875-001
Product Specification	PS-73780-999-001
Sales Drawing	SD-73769-001-001

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